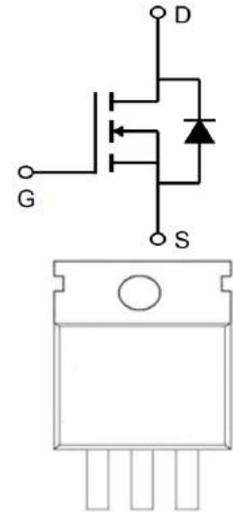


## 600V N-Channel Enhancement Mode MOSFET

### Description

The 11N60 is silicon N-channel Enhanced VDMOSFETs, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency.



### General Features

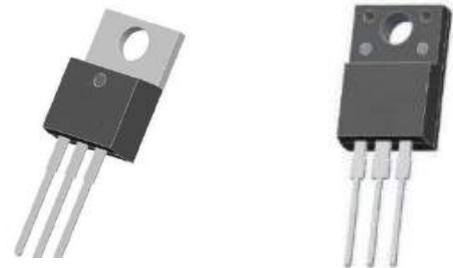
$V_{DS} = 600V, I_D = 11A$

$R_{DS(ON)} < 620m\Omega @ V_{GS} = 10V$

### Application

Uninterruptible Power Supply(UPS)

Power Factor Correction (PFC)



### Absolute Maximum Ratings $T_C = 25^\circ C$ , unless otherwise noted

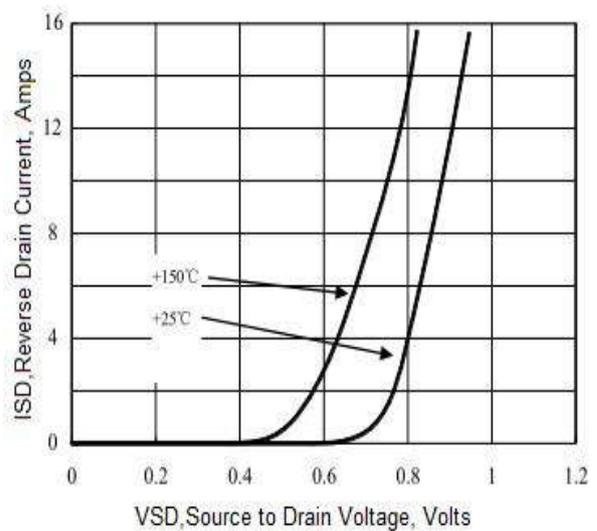
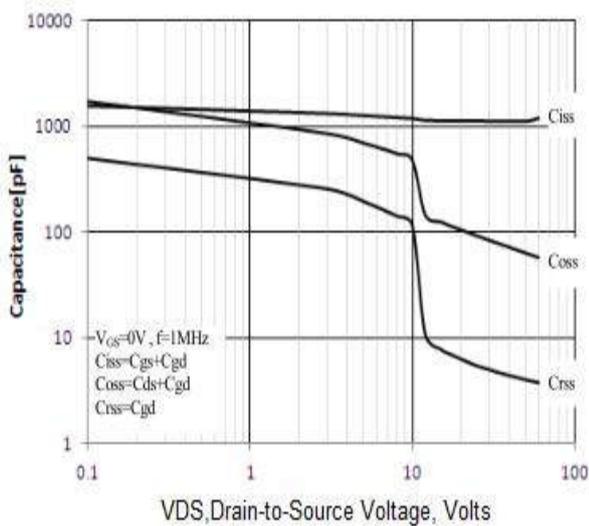
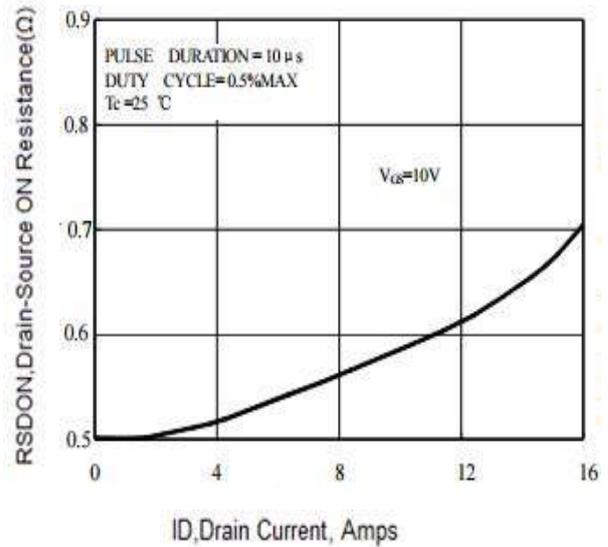
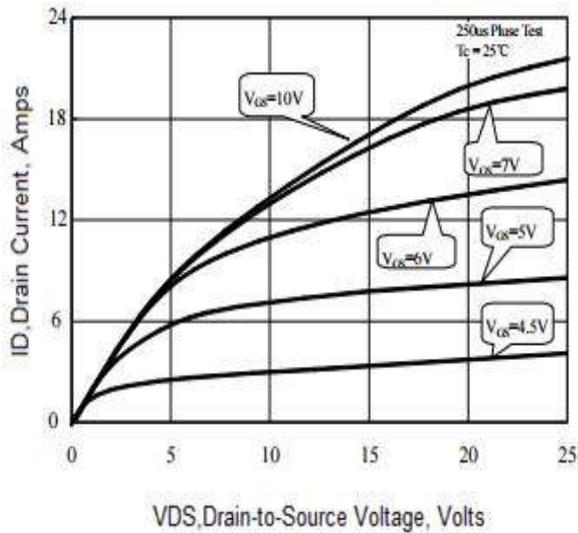
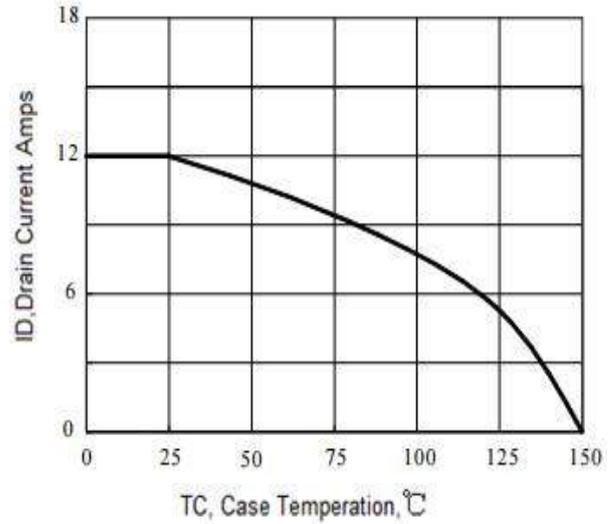
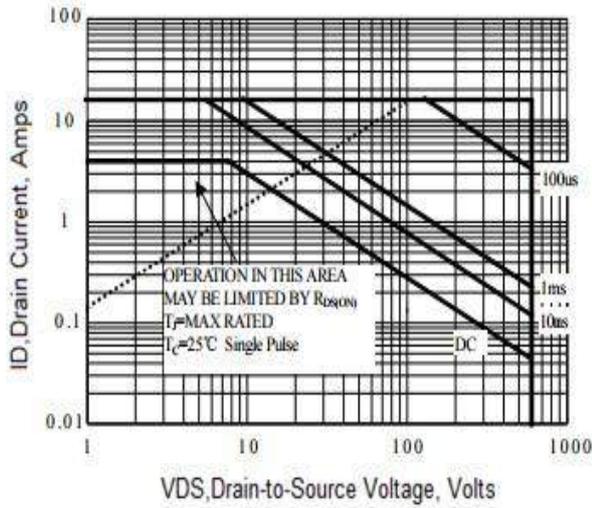
Symbol	Characteristics	Value		Unit
		TO-220F	TO-220	
$V_{DS}$	Drain-Source Voltage	600		V
$V_{GS}$	Gate-Source Voltage	$\pm 30$		V
$I_D$	Continue Drain Current	11		A
$I_{DM}$	Pulsed Drain Current (Note1)	48		A
$P_D$	Power Dissipation	55	140	W
$E_{AS}$	Single Pulse Avalanche Energy (Note1)	660		mJ
$T_J$	Operating Temperature Range	150		$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to +150		$^\circ C$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.27	0.89	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	100	62	$^\circ C/W$

**600V N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics (T<sub>A</sub>=25 °C unless otherwise noted)**

Symbol	Characteristics	Test Condition	Min	Typ	Max	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	600	-	-	V
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	-	-	1	μA
IGSS	Gate Leakage Current	V <sub>GS</sub> = ± 30 V, V <sub>DS</sub> = 0 V	-	-	± 100	nA
VGS(th)	Gate-Source Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	-	4	V
RDS(on)	Drain-Source On-State Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A	-	510	620	mΩ
gfs	Forward Transconductance	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 6 A	-	12	-	S
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz	-	1540	-	pF
C <sub>oss</sub>	Output Capacitance		-	180	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	8	-	pF
td(ON)	Turn-on Delay Time(Note2)	I <sub>D</sub> = 12 A, V <sub>DD</sub> = 300 V, R <sub>G</sub> = 10 Ω	-	16	-	ns
t <sub>r</sub>	Rise Time(Note2)		-	26	-	ns
td(OFF)	Turn-Off Delay Time(Note2)		-	65	-	ns
t <sub>f</sub>	Fall Time(Note2)		-	40	-	ns
Q <sub>G</sub>	Total Gate Charge(Note2)	I <sub>D</sub> = 12 A, V <sub>DD</sub> = 480 V, V <sub>GS</sub> = 10 V	-	44	-	nC
Q <sub>GS</sub>	Gate to Source Charge(Note2)		-	10	-	nC
Q <sub>GD</sub>	Gate to Drain Charge(Note2)		-	16	-	nC
IS	Maximun Body-Diode Continuous Current		-	-	12	A
ISM	Maximun Body-Diode Pulsed Current(Note2)		-	-	48	A
VSD	Drain-Source Diode Forward Voltage	I <sub>SD</sub> = 12 A	-	-	1.5	V
trr	Reverse Recovery Time(Note2)	I <sub>SD</sub> = 12 A, V <sub>GS</sub> = 0 V, dI <sub>F</sub> / dt = 100 A/μs	-	324	-	ns
Qrr	Reverse Recovery Charge(Note2)		-	2.5	-	μC

Note2:Pulse test: 300 μs pulse width, 2 % duty cycle

## 600V N-Channel Enhancement Mode MOSFET



## 600V N-Channel Enhancement Mode MOSFET

